EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	34	((semiconductor wafer ic integrated chip multichip die dice) and (carrier module mcm ((wir$6 packag$6) near substrate)) and (rwl rdl redistribut$6 rewiring) and (solder near2 (ball bump$6 resist))).clm.	US-PGPUB	OR	ON	2006/02/09 15:58
S1	2	"6140707".pn. "6573598".pn.	US-PGPUB; USPAT	OR	OFF	2006/02/08 17:04
S2	6	de-10138042-$.did. de-19702014-$.did. de-19960249-$.did. jp-2001332653-$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2006/02/09 09:40
S3	9384	438/107.ccls. 438/108.ccls. 438/125.ccls. 438/613.ccls. 257/701.ccls. 257/723.ccls. 257/738.ccls. 257/778.ccls.	US-PGPUB; USPAT	OR	OFF	2006/02/09 09:43
S4	1017	438/125.ccls.	US-PGPUB; USPAT	OR	OFF	2006/02/09 10:41
S5	267	S3 and (rwl ((redistribut$6 rewiring) near2 (line trace interconnect$6 wir$6 conductor metal$8)))	US-PGPUB; USPAT	OR	ON	2006/02/09 12:31
S6	14	(semiconductor wafer ic integrated) and (((chip multichip die dice) near2 (carrier module)) mcm ((wir$6 packag$6) adj substrate)) and (rwl ((redistribut$6 rewiring) near2 (line trace interconnect$6 wir$6 conductor metal$8)))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/09 10:52
S7	21	(((chip multichip die dice) near2 (carrier module)) mcm ((wir$6 packag$6) adj substrate)) and (rwl ((redistribut$6 rewiring) near2 (line trace interconnect$6 wir$6 conductor metal$8)))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/09 10:55
S8	98	(semiconductor wafer ic integrated) and ((((chip multichip die dice) near2 (carrier module)) mcm ((wir$6 packag$6) adj substrate)) same (rwl ((redistribut$6 rewiring) near2 (line trace interconnect$6 wir$6 conductor metal$8))))	US-PGPUB; USPAT	OR	ON	2006/02/09 15:54

EAST Search History

S9	101	(((chip multichip die dice) near2 (carrier module)) mcm ((wir$6 packag$6) adj substrate)) same (rwl ((redistribut$6 rewiring) near2 (line trace interconnect$6 wir$6 conductor metal$8)))	US-PGPUB; USPAT	OR	ON	2006/02/09 12:32
S10	30	(((chip multichip die dice) near4 (carrier module)) mcm ((wir$6 packag$6) near2 substrate)) and (rwl ((redistribut$6 rewiring) near2 (line trace interconnect$6 wir$6 conductor metal$8)))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/09 12:24
S11	177	(rwl ((redistribut$6 rewiring) near2 (line trace interconnect$6 wir$6 conductor metal$8))).clm.	US-PGPUB	OR	ON	2006/02/09 12:33
S12	101	S11 and (solder ball bump$6).clm.	US-PGPUB	OR	ON	2006/02/09 12:34
S13	134	S11 and (((chip multichip die dice) nea4 (carrier module)) mcm ((wir$6 packag$6) near2 substrate)).clm.	US-PGPUB; USPAT	OR	ON	2006/02/09 12:34
S14	83	S12 and (((chip multichip die dice) nea4 (carrier module)) mcm ((wir$6 packag$6) near2 substrate)).clm.	US-PGPUB; USPAT	OR	ON	2006/02/09 12:36